

**Moisture Sensitivity Level (MSL) change for DFN, QFN Packages  $\leq$  5x5mm**

**TYPE OF CHANGE:**

MSL change from

- - MSL3 = soldering permitted within 168h (=floor life time) after removal from Moisture Barrier Bag if stored at 30°C / 60%RH or below
- to
- - MSL1 = not moisture sensitive / no Moisture Barrier Bag necessary

**REASON FOR CHANGE:**

- Improved handling conditions by relaxed floor live time limitations.

**PRODUCTS CONCERNED:**

- package types DFN, QFN / outline  $\leq$  5x5mm, products qualified or adopted be generic data (see: CHARACTERIZATION and MARKING):

**CLASSIFICATION:**

- Minor change (information necessary)

**QUALIFICATION:**

- Preconditioning MSL1 J-STD 020: 85°C / 85%RH / 168h
- 3x Convection reflow with 260°C peak temperature
- JESD22-A104: 1000x -55°C / +150°C temperature cycle
- JESD22-A118: 130°C / 85%RH / 96h UHST
- SAM Analysis

**CHARACTERIZATION:**

- No influence on current specifications releases.
- Check RoHS status list at <http://www.ichaus.com> for individual MSL information.

**SCHEDULE OF CHANGE:**

- First delivery: planned for February 2008

**MARKING:**

- MSL mark on label on static shield bag